



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



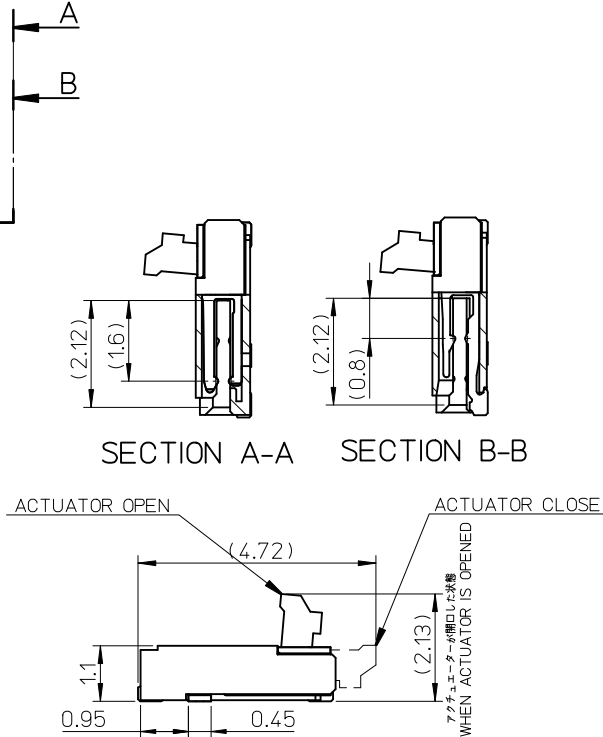
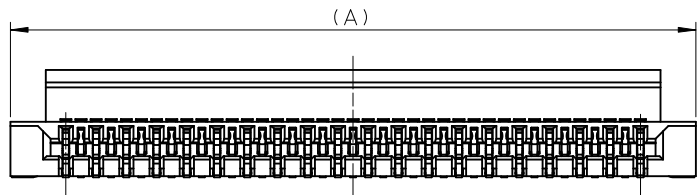
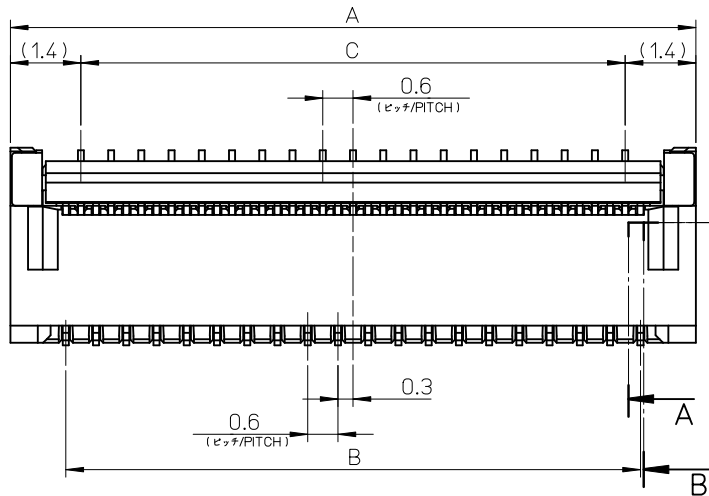
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

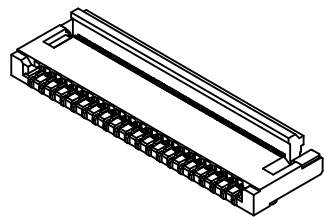




部品構成
PART COMPOSITION

- ハウジング: 液晶ポリマー (LCP), ガラス充填, UL94 V-0, ナチュラル (白)
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94 V-0, NATURAL (WHITE)
- 奇数ターミナル: 銅合金
ODD TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH: PARTLY GOLD OVER NICKEL PLATING NI STRIPE(BARRIER)
- 偶数ターミナル: 銅合金
EVEN TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH: PARTLY GOLD OVER NICKEL PLATING NI STRIPE(BARRIER)
- アクチュエータ...材質: ポリアミド(PA) 黒色 UL94V-0
ACTUATOR MATERIAL: POLYAMIDE(PA) BLACK UL94-V0
- ネイル...材質: 磷青銅
NAIL MATERIAL: PHOSPHOR BRONZE
処理: ニッケル下地すずめっき
FINISH: TIN OVER NICKEL PLATING
- ELV及びRoHS適合品
ELV & RoHS COMPLIANT

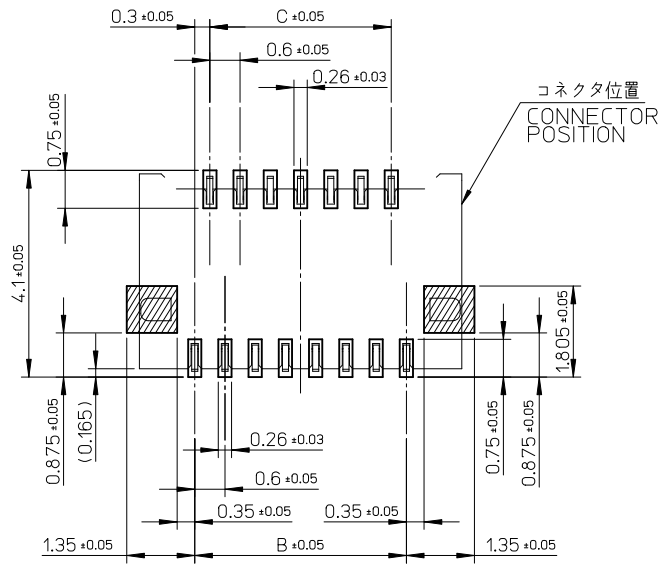
15.6	14.4	15	17.2	502350-5100	51
14.4	13.2	13.8	16.0	502350-4700	47
13.8	12.6	13.2	15.4	502350-4500	45
12.6	11.4	12	14.2	502350-4100	41
12	10.8	11.4	13.6	502350-3900	39
11.4	10.2	10.8	13	502350-3700	37
10.2	9	9.6	11.8	502350-3300	33
9.6	8.4	9	11.2	502350-3100	31
7.2	6	6.6	8.8	502350-2300	23
6	4.8	5.4	7.6	502350-1900	19
4.8	3.6	4.2	6.4	502350-1500	15
D	C	B	A	EMBOSSED PACKAGE	極数
				オーダー番号 ORDER NO.	CIRCUITS



斜視図
SCALE 5:1

CONNECTOR SERIES No. 502350-**09

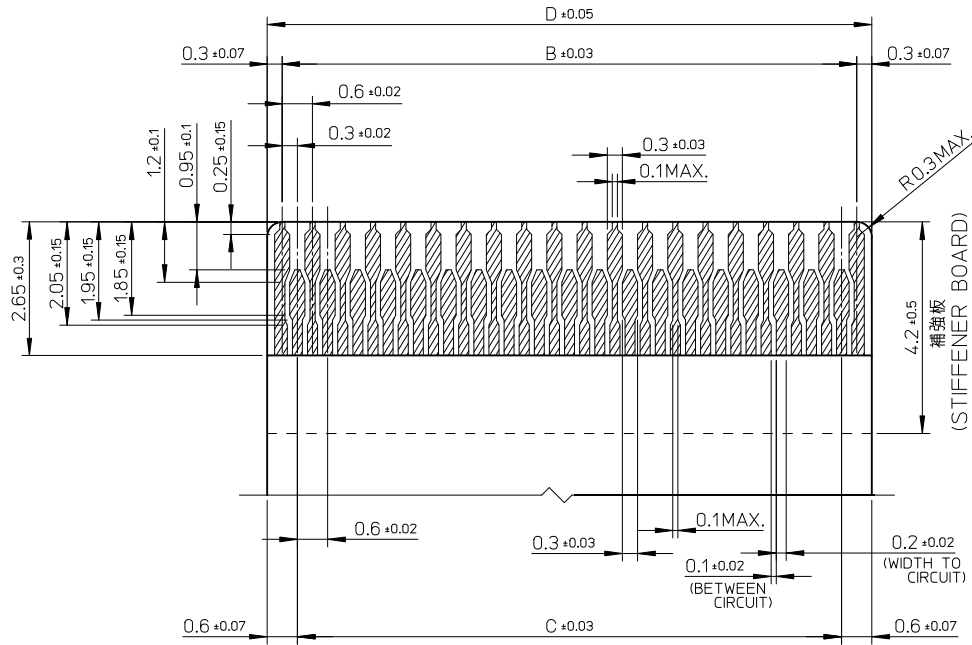
REVISED EC NO.: J2011-0598 DRW: SHIRATA 2010/10/19 CHKD: TAKAHASHI 2010/10/19 APPR: KMORIKAWA 2010/10/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. HIRAYAMA	DATE 2009/01/05	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE	
	10 OVER 30 UNDER	±0.25	CHECKED BY N. MATSUURA	DATE 2009/01/05	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/10/25	DOCUMENT NO. SD-502350-001	SHEET NO. 1 OF 2
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



参考基板レイアウト (マウント面)

P.C. BOARD PATTERN DIM.(REF.)

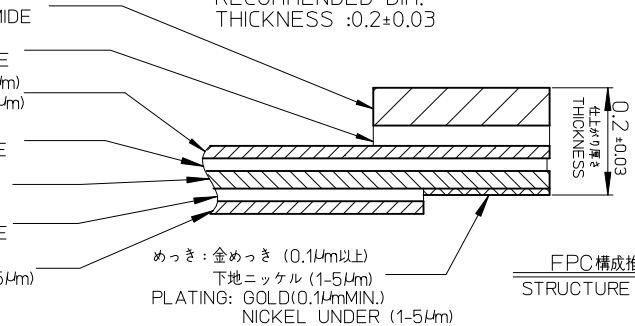
推奨メタルマスク厚さ : 0.1mm
 RECOMMENDED METAL MASK THICKNESS : 0.1mm
 推奨開口率 : 100%
 APERTURE RATE : 100%



適合FPC推奨寸法

仕上がり厚さ : 0.2±0.03
 APPLY FPC
 RECOMMENDED DIM.
 THICKNESS : 0.2±0.03

補強板: ポリイミド
 REINFORCE BOARD: POLYIMIDE
 熱硬化接着剤
 THERMOSETTING ADHESIVE
 ベースフィルム: ポリイミド (25μm)
 BASE FILM: POLYIMIDE (25μm)
 熱硬化接着剤
 THERMOSETTING ADHESIVE
 導体部: 銅箔 (35μm)
 COPPER FOIL (35μm)
 熱硬化接着剤
 THERMOSETTING ADHESIVE
 カバーレイ: ポリイミド (25μm)
 COVER FILM: POLYIMIDE (25μm)



FPC構成推奨仕様
 STRUCTURE OF FPC

注記
 NOTE

- 基板実装前にアクチュエータを操作しないで下さい。
 PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
- 必ず基板に実装してからアクチュエータを操作して下さい。
 PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE.
- FPCについて
 ABOUT FPC

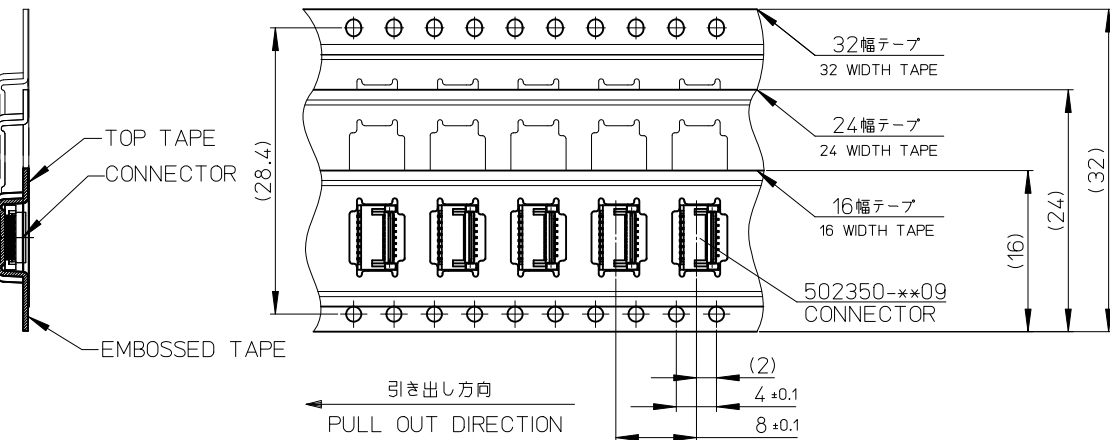
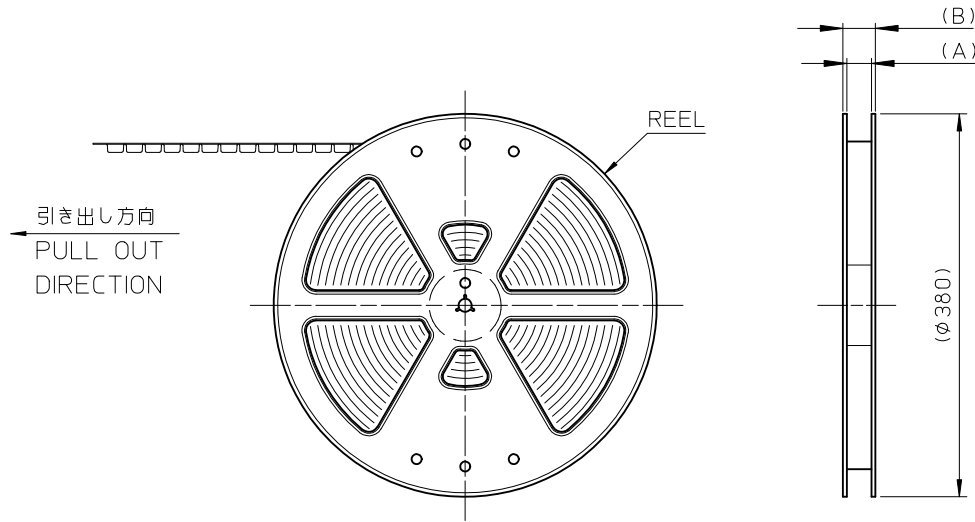
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
 接着剤は熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
 NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

打抜き方向は導体側から補強板側を推奨致します。
 導体部については軟銅箔35μmまたは50μmを推奨致します。

RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED CONDUCTOR SPECIFICATION:
 THICKNESS OF SOFT COPPER FOIL: 35MICROMETER OR 50 MICROMETER

- 平坦度は0.1以下
 COPLANARITY TO BE 0.1 MAXIMUM

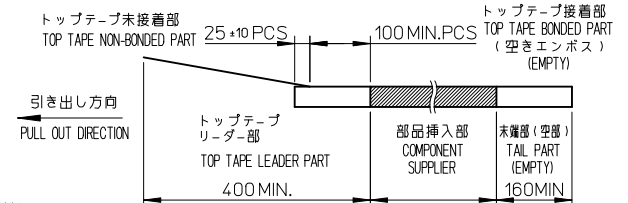
REVISED EC NO.: J2011-0598 DRW: SHIRATA 2010/10/19 CHKD: TAKAHASHI 2010/10/19 APPR: KMORIKAWA 2010/10/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. HIRAYAMA	DATE 2009/01/05	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE	
	10 OVER 30 UNDER	±0.25	CHECKED BY N. MATSUURA	DATE 2009/01/05	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/10/25	DOCUMENT NO. SD-502350-001	SHEET NO. 2 OF 2
REV	DESCRIPTION	ANGULAR ±3 °	MATERIAL NO. SEE CHART1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						



エンボステープ内の製品の向き
DIRECTION OF CONNECTOR IN EMBOSSED TAPE

NOTES

- 製品 (502350-**09) の詳細寸法については、図面 SD-502350-001をご参照下さい。
IN THE PACKAGE, PART NO. 502350-**09 DETAILED DIMENSIONS. REFER TO SALES DRAWING NO. SD-502350-001.
- 梱包数量 : 3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
キャリアテープ : ポリスチレン (PS)
トップテープ : PET, OTHER
リール : ポリスチレン (PS) <リサイクル材を含む>
MATERIAL
CARRIER TAPE : POLYSTYRENE(PS)
TOP TAPE : PET, OTHER
REEL : POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
- トップテープの剥離強度については、IEC60286-3に準拠
Top tape peel force is defined by IEC60286-3.

37.4	33.4	32	502350-5100	51
			502350-4700	47
			502350-4500	45
			502350-4100	41
			502350-3900	39
			502350-3700	37
			502350-3300	33
			502350-3100	31
			502350-2300	23
			502350-1900	19
29.4	25.4	24	502350-1500	15
21.4	17.4	16	502350-1500	15
B	A	WIDTH TAPE	EMBOSSED PACKAGE	CIRCUIT
			オーダー番号	ORDER NO.

REVISED EC NO.: J2011-0598 DRW:SHIRATA 2010/10/19 CHKD:KAKAHASHI 2010/10/19 APPR:KMORIKAWA 2010/10/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MODEL NO.		
				MM ONLY		---	METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE				
		10 OVER 30 UNDER	± 0.25	T. HIRAYAMA	2009/01/05	0.3 FPC CONN. H=1.1 EMBSTP PKG				
30 OVER	± 0.3	CHECKED BY	DATE	MOLEX INCORPORATED						
		N. MATSUURA	2009/01/05	SEE CHART						
		APPROVED BY	DATE	SD-502350-002						
		KMORIKAWA	2010/10/25	1 OF 1						
		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						